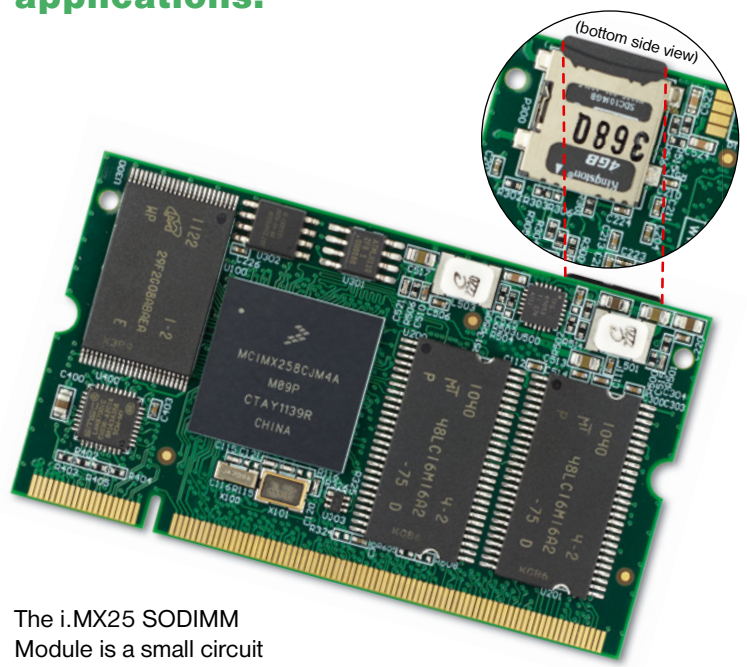
# i.MX25 SODIMM Module

**This cost-effective i.MX25 module with preinstalled operating system represents the III. generation of the embedded devices from Voipac, that have been increasingly attracting interest of various industry segment users because of the quick set-up and easy-to-handle programming of own applications.**




The i.MX25 SODIMM Module is a small circuit board which belongs to the group of COMs (Computer On Module). Central component is the i.MX25 processor from Freescale that provides the module with enough computing power to cover majority of the industrial applications requirements. The module can be plugged into a standard 200pin SODIMM connector which allows base board components to be placed even beneath the module. This 1 mm thick 8-layer microcontroller board includes all of the technologically and development demanding parts, saving many man-months of the high-frequency PCB design, complex prototyping, debugging and OS porting, thus minimizing the time-to-market of the customers' own devices.

For the customers' safety, the module is compatible with the main competitors' solutions, providing the necessary flexibility and a guarantee of the second source availability. Above the specification of the currently available i.MX25 based SODIMM solutions, Voipac's i.MX25 SODIMM module provides: higher maximum memory configuration, SD switch, I2C EEPROM, SPI FLASH and microSD socket soldered right on the module in order not to limit the customers' future memory requirements.

As usually, all of the available software and base board schematic is available for free download at the Voipac Downloads page. As the only manufacturer in the embedded COM segment, **Voipac provides complete schematic of the module itself to every complete development kit purchased for no extra charge.**

## Hardware Specification

| | |
|---|---|
| **CPU:** | **i.MX25 (Freescale) up to 400 MHz, ARM9** |
| **NAND FLASH:** | **128/256/512 MB** |
| **SDRAM:** | **16/32/64/128 MB** |
| **I2C EEPROM:** | **512 Kb** |
| **SPI FLASH:** | **16/32 Mb** |
| **Ethernet:** | **10/100 Mbps** |
| **Power supply:** | **single 3.6 V to 5.5 V** |
| **Form factor:** | **200pin SODIMM** |
| **Dimensions:** | **67.6 x 38.0 mm** |
| **Temperature range:** | **Commercial 0°C to +70°C** |
| | **Extended -20°C to +70°C** |
| *(excluding microSD socket)* | **Industrial -40°C to +85°C** |
| **microSD socket:** | **on module** |
| **RoHS compliant** | |

## Key Features

**High-Speed USB 2.0 OTG**
**Full-Speed USB 2.0 Host**
**LCD controller supporting SVGA 800x600**
**4-wire touch screen**
**Still-picture camera interface**
**UART**
**MMC / SD / microSD Card**
**I2C**
**PWM**
**Digital Audio IN/OUT**
**Configurable serial peripheral interface**
**CAN**

## Supported Software

**OS Linux 2.6** *(preinstalled)*
**Windows CE 6.0 Embedded** *(optional)*
**Android Gingerbread 2.3** *(optional)*

Windows® Embedded Partner

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